

**IN THE SPECIFICATION:**

**Pl as r plac th paragraph beginning at pag 17, lin 17, with the f llowing rewritten paragraph:**

According to a 26th aspect of the present invention, there is provided a semiconductor device-mounted component manufacturing apparatus as defined in the 25th aspect, wherein

**Please replace the paragraph beginning at page 38, line 23, with the following rewritten paragraph:**

Even in this fourth embodiment, the semiconductor device package, which has the total thickness of those of the semiconductor device 3 and the thermoplastic resin portion, can be remarkably reduced in thickness, dissimilar to the semiconductor device package shown in the prior art example of Fig. 21. Moreover, because of the absence of the conductive adhesive 16 and the encapsulant 21 shown in Fig. 21 and because of no time required for the hardening of the conductive adhesive and the encapsulant, the productivity can be remarkably improved. Furthermore, a multi-layered high-density semiconductor package can be supplied at low cost.